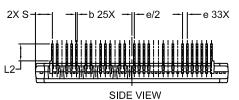
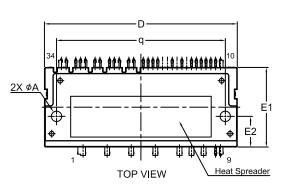
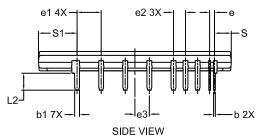


## DIP34 80x33, AUTOMOTIVE MODULE CASE MODGL ISSUE O

**DATE 19 OCT 2018** 

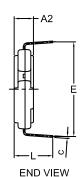






## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.



	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
A2	7.90	8.00	8.10	
b	0.60	0.70	0.80	
b1	1.90	2.00	2.10	
O	0.65	0.70	0.80	
D	79.70	80.00	80.30	
Е	38.76	39.26	39.76	
E1	32.70	33.00	33.30	
E2	12.50	12.70	12.90	
е	1.70	2.00	2.30	
e1	9.70	10.00	10.30	
e2	4.70	5.00	5.30	
e3	5.70	6.00	6.30	
Г	15.50	16.00	16.50	
L2	6.70	7.00	7.30	
q	69.75	70.00	70.25	
S	7.00 REF			
S1	16.00 REF			
ΦA	4.10	4.30	4.50	

## GENERIC MARKING DIAGRAM\*

XXXXXXXXXX ZZZ ATYWW NNNNNNN XXXX = Specific Device Code

ZZZ = Lot ID

AT = Assembly & Test Location

Y = Year

W = Work Week

NNN = Serial Number

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION: DIP34 80x33, AUTOMOTIVE MODULE		PAGE 1 OF 1	

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